

Abstract

Wire loop, semiconductor device having same, wire bonding method and wire bonding apparatus

A wire loop comprises a wire (3) connecting a first bonding point (A) and a second bonding point (Z) therethrough, wherein the wire (3) has a crushed part (3c) formed therein by crushing the part of the wire (3) and a top of a ball (30) bonded to the first bonding point (A) with a capillary (4). The wire loop is formed by a wire bonding method which includes: bonding the wire (3) to the first bonding point (A); moving the capillary (4) horizontally and vertically while carrying out loop control; bonding the wire (3) to the vicinity of the top of the ball (30) bonded to the first bonding point (A); and thereafter, moving the capillary (4) horizontally and vertically to the second bonding point (Z) while delivering the wire (3) and carrying out loop control, and then bonding the wire (3) to the second bonding point (Z).

FIG. 1